


- ① Substrate: 1.59mm ± 0.18mm [0.0625" ± 0.007"] FR4/G10 or equivalent high temp material.
- ② Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).

**Description:** Giga-snaP BGA SMT Land Socket  
 256 position BGA surface mount land pattern to terminal pins (1.0mm [0.039"] centers, 16X16 array)

**Tolerances:** diameters ± 0.03mm [± 0.001"], PCB perimeters ± 0.13mm [± 0.005"], PCB thicknesses ± 0.18mm [± 0.007"], pitches (from true position) ± 0.08mm [± 0.003"], all other tolerances ± 0.13mm [± 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

<b>LS-BGA256E-41 Drawing</b>		Status: Released	Scale: 4:1	Rev: B
 © 2005 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: S Natarajan		Date: 3/2/05	
	File: LS-BGA256E-41 Dwg		Modified: 4/18/05	